



Materials Declaration Form


IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	14-06-2021
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	MDG MD CHAMPION	Representative Title	MDG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement	
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Legal Statement	
Supplier Acceptance *	true
Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
M24256-BRDW6P	PT6P*2456BKB	A	3068	14-06-2021
	Amount	UoM	Unit type	ST ECOPACK Grade
	34.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
TSSOP	NAC	8	L Bend	
Comment	Package : 6P TSSOP 8 BODY 4.4 PITCH 0.65 0079397			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-19th January 2021				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	PT6P*2456BKB				7000001.0	999999.7
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	1.238	mg	supplier	die	Silicon (Si)	7440-21-3		1.191	mg	962036	35029
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	3231	118
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	808	29
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	808	29
				supplier	Passivation	Silicon Nitride	12033-89-5		0.003	mg	2423	88
Lead-frame	M-011 Other inorganic materials	14.517	mg	supplier	Passivation	Silicon Oxide	7631-86-9		0.038	mg	30695	1118
				supplier	alloy	Copper (Cu)	7440-50-8		14.147	mg	974500	416079
				supplier	alloy	Iron (Fe)	7439-89-6		0.341	mg	23460	10017
				supplier	alloy	Zinc (Zn)	7440-66-6		0.017	mg	1200	512
Lead-frame Coating	M-011 Other inorganic materials	0.062	mg	supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.012	mg	840	359
				supplier	coating	Nickel (Ni)	7440-02-0		0.058	mg	942580	1708
				supplier	coating	Palladium (Pd)	7440-05-3		0.002	mg	29665	54
				supplier	coating	Gold (Au)	7440-57-5		0.002	mg	27755	50
Die Attach	M-011 Other inorganic materials	0.049	mg	supplier	glue or soft solder	Silver(Ag)	7440-22-4		0.037	mg	760000	1095
				supplier	glue or soft solder	Oxiranylmethoxy-phenyl-methylene-bisoxiran	13561-08-5		0.006	mg	120000	173
				supplier	glue or soft solder	Phenol resin	9003-35-4		0.001	mg	30000	43
				supplier	glue or soft solder	Epoxypropoxy butane polymer	2425-79-8		0.001	mg	30000	43
				supplier	glue or soft solder	Diglycidyl phenyl allyl ether	EC 417-470-1		0.002	mg	50000	72
Wires	M-011 Other inorganic materials	0.019	mg	supplier	glue or soft solder	Polyoxypropylenediamine	9046-10-0		0.000	mg	10000	14
				supplier	Bonding wire	Gold (Au)	7440-57-5		0.019	mg	1000000	546
				supplier	Moulding Compound	Epoxy Resin	Proprietary		1.434	mg	79172	42183
				supplier	Moulding Compound	Phenol Resin	Proprietary		0.956	mg	52781	28122
				supplier	Moulding Compound	Silica, vitreous	60676-86-0		15.553	mg	858547	457438
Encapsulation	M-011 Other inorganic materials	18.115	mg	supplier	Moulding Compound	Carbon black	1333-86-4		0.096	mg	5278	2812
				supplier	Moulding Compound	Bismuth (Bi)	7440-69-9		0.076	mg	4222	2250
				supplier	Moulding Compound							
				supplier	Moulding Compound							
Finishing	M-011 Other inorganic materials	0.001	mg	supplier	connections coating	Nickel (Ni)	7440-02-0		0.001	mg	940951	17
				supplier	connections coating	Palladium (Pd)	7440-05-3		0.000	mg	30507	1
				supplier	connections coating	Gold (Au)	7440-57-5		0.000	mg	28542	1

